



Initial Product/Process Change Notification

Document #: IPCN23660XH

Issue Date: 18 May 2023

Title of Change:	Additional wafer fabrication facility for ONBCD25 technology in onsemi Aizu located in Aizu, Japan.	
Proposed First Ship date:	15 Jan 2024 or earlier if approved by customer	
Contact Information:	Contact your local onsemi Sales Office or Jonathan.Bass@onsemi.com	
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < PCN.Support@onsemi.com >	
Marking of Parts/ Traceability of Change:	No change to marking / Changed material may be identified by date code	
Change Category:	Wafer Fab Change	
Change Sub-Category(s):	Manufacturing Site Addition	
Sites Affected:		
onsemi Sites	External Foundry/Subcon Sites	
onsemi Aizu, Japan	None	
Description and Purpose:		
onsemi would like to inform its customers that we will be qualifying an additional wafer fabrication facility for ONBCD25 technology in onsemi Aizu, Japan for the devices listed in this IPCN. The wafer technology was previously qualified in 2021 and multiple products are already running production on this flow. These changes can be found under FPCN23660X-XF. Upon completion of the qualification, all products listed here will be dual sourced from its current wafer fab facility in onsemi wafer fab in Gresham, US or onsemi, Aizu, Japan		
	From	To
Fab Site	onsemi Gresham, US	onsemi Gresham, US or onsemi Aizu, Japan
There will be no change to the orderable part number.		
There will be no product marking change as a result of this change		



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Qualification Plans:

QV DEVICE NAME: SCY99261ABAZZAMN1TBG

RMS: S90987

PACKAGE: DFN8 AU SNGL HPBF

Test	Specification	Condition	Interval
High Temperature Operating Life	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C	
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs

QV DEVICE NAME SCY99218EAHBB0DR2G

RMS: O77064

PACKAGE: SOIC-8

Test	Specification	Condition	Interval
High Temperature Operating Life	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260°C	
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs

QV DEVICE NAME: NCP4318ALKDR2G

RMS: O90520

PACKAGE: SOIC-8

Test	Specification	Condition	Interval
High Temperature Operating Life	JESD22-A108	Ta=105°C, 100 % max rated Vcc	1008 hrs
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C	-
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	1000 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs

QV DEVICE NAME: NCV6324BMTAAWTBG

RMS: S90590

PACKAGE: WDFN8 AU SNGL HPBF WFS

Test	Specification	Condition	Interval
High Temperature Operating Life	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs
Early Life Failure Rate	JESD22-A108	Ta=125°C, 100 % max rated Vcc	48 hrs
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C	
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	1000 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs

QV DEVICE NAME: AX71551MNZ

RMS: O90959

PACKAGE: QFN 48 7x7

Test	Specification	Condition	Interval
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hours
Preconditioning	J-STD-020 JESD-A113	MSL 3 @ 260 °C	
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cycles
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hours
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hours

QV DEVICE NAME: NCP3237MNTXG

RMS: O71343

PACKAGE: QFN18

Test	Specification	Condition	Interval
High Temperature Operating Life	JESD22-A108	Ta=95°C, Tj=150°C, Vdd=15V	504 hours
Early Life Failure Rate	JESD22-A108	Ta=95°C, Tj=150°C, Vdd=15V	504 hours
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hours
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C	
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cycles
Highly Accelerated Stress Test	JESD22-A110	110°C, 85% RH, biased	264 hours
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hours

Estimated date for qualification completion: **16 October 2023**



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List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
NCP4305AMTTWG	SCY99261ABAZZAMN1TBG
NCP4305DMNTWG	SCY99261ABAZZAMN1TBG
NCP4305DMTTWG	SCY99261ABAZZAMN1TBG
NCP4306AAAZZADR2G	SCY99218EAHBB0DR2G
NCP4306AAAZZAMN1TBG	SCY99261ABAZZAMN1TBG
NCP4306AAAZZAMNTWG	SCY99261ABAZZAMN1TBG
NCP4306AADZZADR2G	SCY99218EAHBB0DR2G
NCP4318AHJDR2G	NCP4318ALKDR2G
NCP4318ALCDR2G	NCP4318ALKDR2G
NCP4318ALLDR2G	NCP4318ALKDR2G
NCP4318ALSDR2G	NCP4318ALKDR2G
NCP4318BLCDR2G	NCP4318ALKDR2G
NCP6323DMTAATBG	NCV6324BMTAAWTBG
NCP6324BMTAATBG	NCV6324BMTAAWTBG
NCP81233MNTXG	NCP3237MNTXG
NCP4318ALKDR2G	NCP4318ALKDR2G
NCP4318AHDDR2G	NCP4318ALKDR2G
NCP43080DMTTWG	SCY99261ABAZZAMN1TBG
NCP43080AMTTWG	SCY99261ABAZZAMN1TBG
NCP43080ADR2G	SCY99218EAHBB0DR2G
NCP4306AAHZZADR2G	SCY99218EAHBB0DR2G
NCP4306AADZZAMNTWG	SCY99261ABAZZAMN1TBG
NCP4306AADZZAMN1TBG	SCY99261ABAZZAMN1TBG

Appendix A: Changed Products

PCN#: IPCN23660XH
Issue Date: May 18, 2023

DIKG: DIGI-KEY

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
NCP4305AMTTWG		SCY99261ABAZZAMN1TBG	N/A	
NCP4306AAAZZADR2G		SCY99218EAHBB0DR2G	N/A	
NCP4306AAAZZAMN1TBG		SCY99261ABAZZAMN1TBG	N/A	
NCP4306AAAZZAMNTWG		SCY99261ABAZZAMN1TBG	N/A	
NCP4306AADZZADR2G		SCY99218EAHBB0DR2G	N/A	
NCP4318AHJDR2G		NCP4318ALKDR2G	N/A	
NCP4318ALCDR2G		NCP4318ALKDR2G	N/A	
NCP4318ALSDR2G		NCP4318ALKDR2G	N/A	
NCP4318BLCDR2G		NCP4318ALKDR2G	N/A	
NCP6324BMTAATBG		NCV6324BMTAAWTBG	N/A	
NCP81233MNTXG		NCP3237MNTXG	N/A	
NCP4318ALKDR2G		NCP4318ALKDR2G	N/A	
NCP4318AHDDR2G		NCP4318ALKDR2G	N/A	
NCP43080DMTTWG		SCY99261ABAZZAMN1TBG	N/A	
NCP43080AMTTWG		SCY99261ABAZZAMN1TBG	N/A	
NCP43080ADR2G		SCY99218EAHBB0DR2G	N/A	
NCP4306AAHZZADR2G		SCY99218EAHBB0DR2G	N/A	
NCP4306AADZZAMNTWG		SCY99261ABAZZAMN1TBG	N/A	
NCP4306AADZZAMN1TBG		SCY99261ABAZZAMN1TBG	N/A	
NCP4305DMNTWG		SCY99261ABAZZAMN1TBG	N/A	
NCP4305DMTTWG		SCY99261ABAZZAMN1TBG	N/A	